

Title (en)
Semiconductor laser device and method of designing the same

Title (de)
Halbleiterlaservorrichtung und zugehöriges Entwurfsverfahren

Title (fr)
Dispositif laser à semi-conducteur et méthode de conception

Publication
EP 0798832 B1 20040218 (EN)

Application
EP 97302080 A 19970326

Priority
• JP 7473796 A 19960328
• JP 25964896 A 19960930

Abstract (en)
[origin: EP0798832A2] A semiconductor laser device comprises a cladding layer of a first conductivity type, an active layer, a cladding layer of a second conductivity type, and a current blocking layer having a stripe-shaped opening having a predetermined width W for restricting a current path and forming the current path, and having a larger band gap than that of the cladding layer of the second conductivity type and having a smaller refractive index than that of the cladding layer of the second conductivity type. A difference Δn between a real refractive index in a region, which corresponds to the opening, in the active layer and a real refractive index in a region, which corresponds to both sides of the opening, in the active layer and the width $W \cdot \mu m$ of the opening are so set as to satisfy a predetermined relationship. The difference Δn between the real refractive indexes is set by selecting the Al composition ratio of the current blocking layer and the thickness of the cladding layer of the second conductivity type on the both sides of the opening. <IMAGE>

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H01S 5/223; **H01S 5/343**

IPC 8 full level
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CPC (source: EP KR US)
B82Y 20/00 (2013.01 - EP US); **G11B 7/1378** (2013.01 - KR); **H01S 5/2205** (2013.01 - KR); **H01S 5/2231** (2013.01 - EP US); **H01S 5/2232** (2013.01 - KR); **H01S 5/204** (2013.01 - EP US); **H01S 5/2206** (2013.01 - EP US); **H01S 5/221** (2013.01 - EP US); **H01S 5/222** (2013.01 - EP US); **H01S 5/32316** (2013.01 - EP US); **H01S 5/3432** (2013.01 - EP US)

Cited by
EP1130722A3; EP1168541A3; US6075802A; US7095769B2

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EP 0798832 A2 19971001; **EP 0798832 A3 19990526**; **EP 0798832 B1 20040218**; CN 1096729 C 20021218; CN 1169047 A 19971231; CN 1255913 C 20060510; CN 1427516 A 20030702; DE 69727608 D1 20040325; DE 69727608 T2 20040923; KR 100468170 B1 20050623; KR 970068066 A 19971013; TW 342545 B 19981011; US 5960019 A 19990928

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